

### ET1856

#### End Termination

##### Description

ET1856 is a solderable & nickel plateable silver/palladium (4:1) end termination designed to be compatible on Multilayer ceramic chip capacitors (NPO and X7R bodies). Nickel plating can be done without pre-plate processing due to the low glass content on the fired surface.

##### Key Features

- Nickel plateable no pre-plate processing Low usage excellent coverage uniformity Dense fired microstructure Cu plateable



*This picture does not show the packaging of ET1856 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

##### Typical Properties

|             |  |
|-------------|--|
| Viscosity   | 30 – 40 Kcps Brookfield RVTSC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C |
| Solids      | 76.5 ± 1 %   |
| Alloy Ratio | 4 : 1  |
| Metal       | AgPd   |

##### Recommended Processing Guide

|                           |   |
|---------------------------|---|
| Drying Temperature        | 150 °C for 10 minutes 20 minute total cycle time                  |
| Process Temperature (TDS) | 650 – 800 °C peak temperature Dwell time of 5 – 7 minutes at peak |
| Recommended Thinner       | RV-372  |

### ET1856

#### End Termination

---

#### Warranty

6 months

#### Storage

Store in a dry location at 5 – 25 °C.

#### Americas

Phone +1 610 825 6050

[electronics.americas@heraeus.com](mailto:electronics.americas@heraeus.com)

#### Asia Pacific

Phone +65 6571 7649

[electronics.apac@heraeus.com](mailto:electronics.apac@heraeus.com)

#### China

Phone +86 53 5815 9601

[electronics.china@heraeus.com](mailto:electronics.china@heraeus.com)

#### Europe, Middle East and Africa

Phone +49 6181 35 4370

[electronics.emea@heraeus.com](mailto:electronics.emea@heraeus.com)

The descriptions and engineering data shown here have been compiled by Heraeus using commonly accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo and Heraeus, figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.

All changes are based on information displayed using the template `data_sheet/HET/TFM/print_data_sheet.html.twig`.  
Version (last updated) 26 Feb 2026

Heraeus Electronics GmbH & Co.KG, 63450 Hanau, Germany  
Web: [www.heraeus-electronics.com](http://www.heraeus-electronics.com)